

# IGBT, FRD

## Bonding Damage During Mounting

---

### Introduction

This application note explains the wire bonding damage that occurs when users assemble IGBT products delivered by Renesas Electronics in bare die or wafer form.

### Contents

|  |   |
|--|---|
| 1. Overview.....                                 | 2 |
| 2. Bonding Damage Examples .....                 | 2 |
| 3. Bonding Damage Limit Evaluation Example ..... | 4 |
| 4. Summary .....                                 | 4 |
| Revision History .....                           | 5 |

## 1. Overview

When assembling Renesas bare die or wafer IGBTs into packages such as modules, inappropriate wire bonding conditions can cause bonding damage, resulting in destruction to the IGBTs and/or surrounding components. There are various causes of bonding damage, including the following examples:

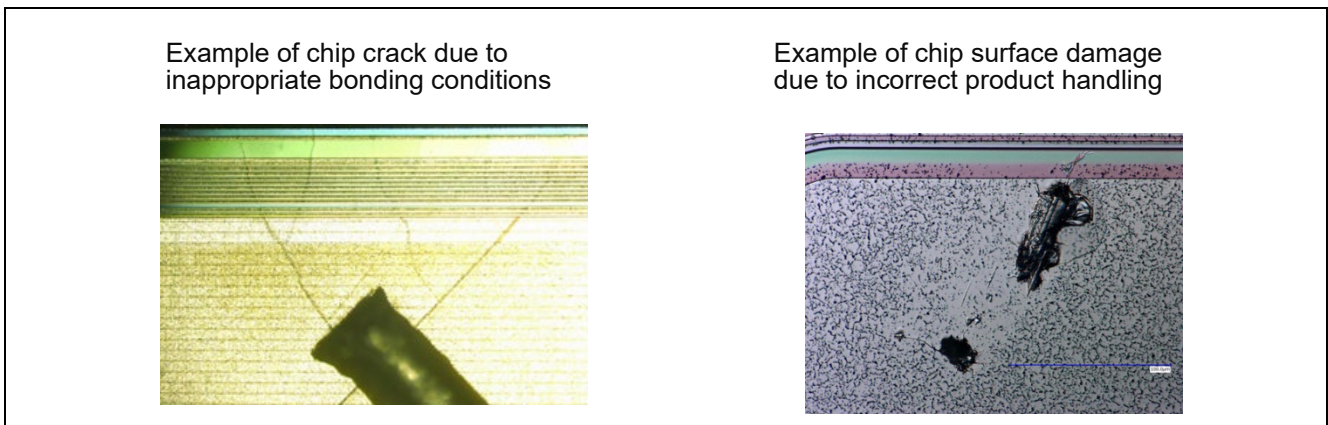
- Misaligned wire bonding resulting in short-circuited electrodes
- Scratched chip surface
- Inappropriate power, load, or other conditions during bonding

Always verify limitation conditions such as bonding damages when setting bonding conditions. These conditions, as well as handling methods, can greatly affect the characteristics fluctuation and reliability of user-assembled products. Also, wire bonding conditions vary greatly depending on the product specifications of our bare die/wafer, user substrate specifications, and wire bonding equipment. Keep in mind that wire bonding conditions also vary greatly depending on the Renesas bare die/wafer product specifications, user board specifications, and wire bonding equipment.

## 2. Bonding Damage Examples

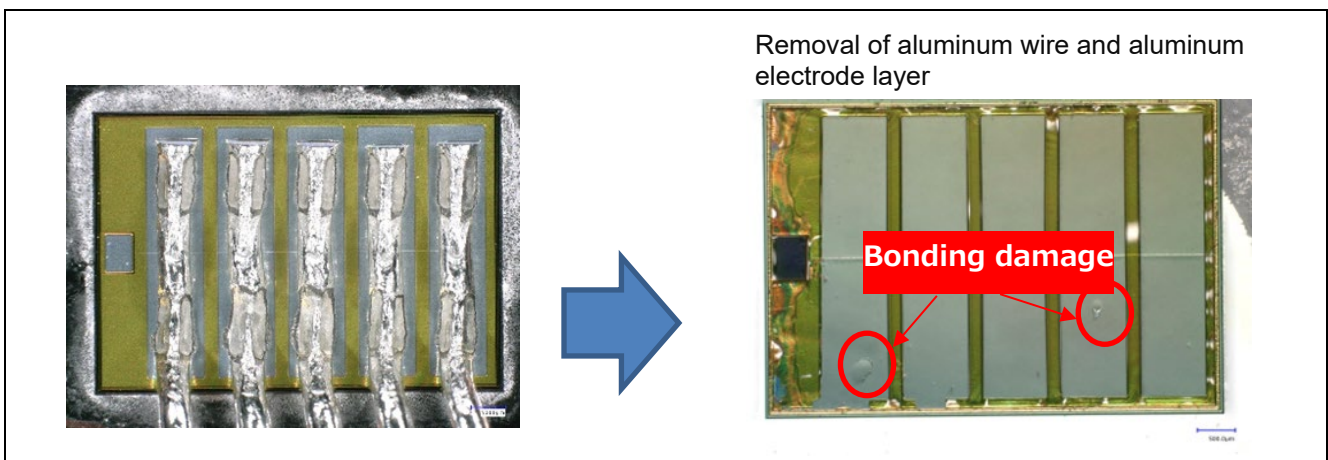
Cells on chips may be damaged due to excessive bonding stress or product handling.

This is an example of visible damage on the chip surface.



**Figure 1 Example of Damage Visible on Chip Surface**

Figure 2 shows an example of cell damage caused by bonding stress that is not externally visible.



**Figure 2 Example of Cell Damage that is Not Externally Visible**

Figure 3 shows an example of localized damage caused by bonding stress.

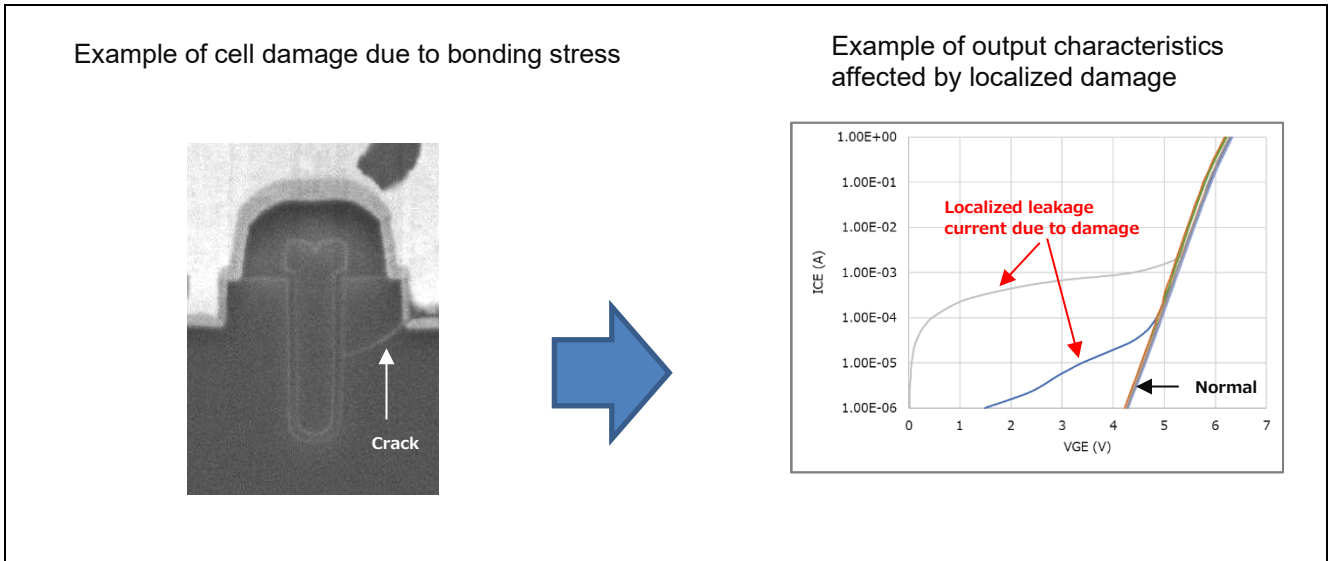


Figure 3 Example of Localized Damage

Figure 4 shows a case study in which we intentionally reproduced a turn-off failure to generate bonding damage.

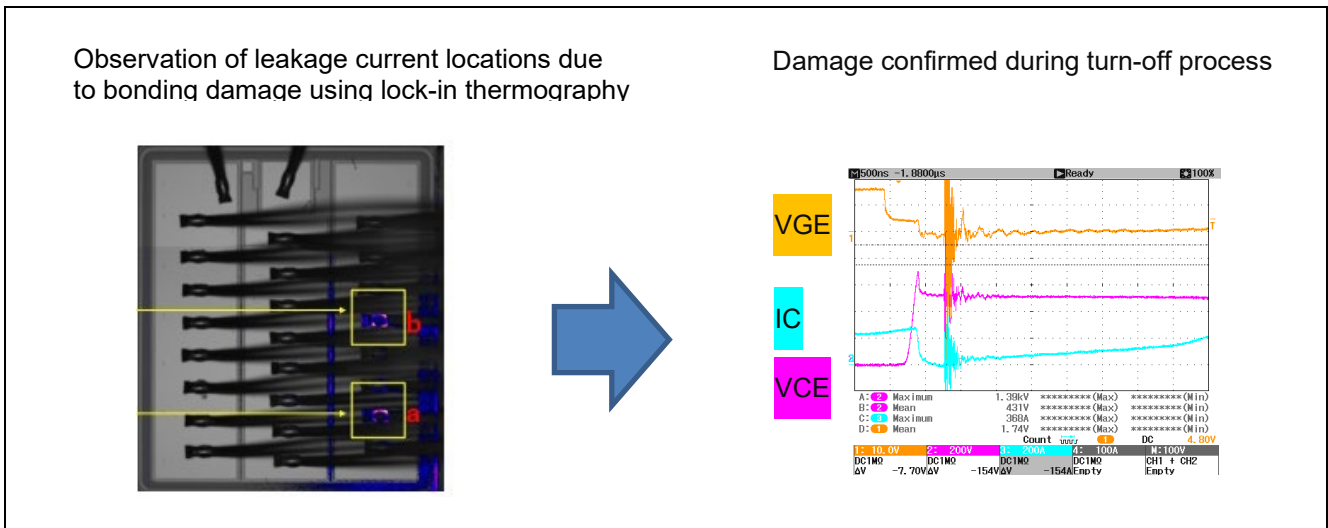


Figure 4 Reproduction of Turn-off Failure Due to Bonding Damage

### 3. Bonding Damage Limit Evaluation Example

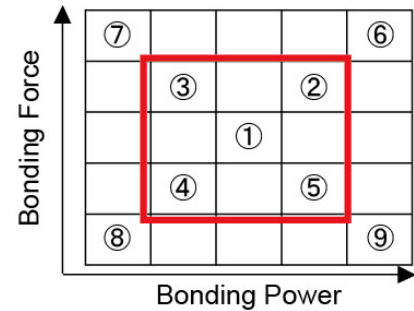
We recommend that a limit evaluation of bonding crimping conditions be performed in advance to avoid bonding damage.

The following is an example of the Renesas limit evaluation.

In general, the likelihood of bonding damage increases as the power and force of the bonding machine are increased. Conversely, lowering both power and force will lead to insufficient bonding strength between wire and chip.

Fine adjustments to bonding conditions may be necessary due to changes in various conditions during the process of sample creation and mass production. For such cases, first estimate conditions (1) to (5) while considering the range of adjustment.

Then estimate (6) to (9) under slightly wider conditions than those in (5) and confirm that bonding damage and insufficient bonding strength do not occur even under these conditions. This verification provides the basis for securing margins.



**Figure 5 Example of Bonding Conditions**

After the above verification, set conditions (1) to (5) as the conditions for sample creation and mass production.

### 4. Summary

When assembling IGBT or FRD products delivered by Renesas Electronics as bare die or in wafer form, we encourage you to check the bonding conditions carefully to avoid the problems presented in this application note and ultimately improve the yield rate of your module assembly.

**Revision History**

| Rev. | Date       | Description |               |
|------|------------|-------------|---------------|
|      |            | Page        | Summary       |
| 1.00 | Dec.2.2024 | -           | First edition |

## Notice

1. Descriptions of circuits, software and other related information in this document are provided only to illustrate the operation of semiconductor products and application examples. You are fully responsible for the incorporation or any other use of the circuits, software, and information in the design of your product or system. Renesas Electronics disclaims any and all liability for any losses and damages incurred by you or third parties arising from the use of these circuits, software, or information.
2. Renesas Electronics hereby expressly disclaims any warranties against and liability for infringement or any other claims involving patents, copyrights, or other intellectual property rights of third parties, by or arising from the use of Renesas Electronics products or technical information described in this document, including but not limited to, the product data, drawings, charts, programs, algorithms, and application examples.
3. No license, express, implied or otherwise, is granted hereby under any patents, copyrights or other intellectual property rights of Renesas Electronics or others.
4. You shall be responsible for determining what licenses are required from any third parties, and obtaining such licenses for the lawful import, export, manufacture, sales, utilization, distribution or other disposal of any products incorporating Renesas Electronics products, if required.
5. You shall not alter, modify, copy, or reverse engineer any Renesas Electronics product, whether in whole or in part. Renesas Electronics disclaims any and all liability for any losses or damages incurred by you or third parties arising from such alteration, modification, copying or reverse engineering.
6. Renesas Electronics products are classified according to the following two quality grades: "Standard" and "High Quality". The intended applications for each Renesas Electronics product depends on the product's quality grade, as indicated below.

"Standard": Computers; office equipment; communications equipment; test and measurement equipment; audio and visual equipment; home electronic appliances; machine tools; personal electronic equipment; industrial robots; etc.

"High Quality": Transportation equipment (automobiles, trains, ships, etc.); traffic control (traffic lights); large-scale communication equipment; key financial terminal systems; safety control equipment; etc.

Unless expressly designated as a high reliability product or a product for harsh environments in a Renesas Electronics data sheet or other Renesas Electronics document, Renesas Electronics products are not intended or authorized for use in products or systems that may pose a direct threat to human life or bodily injury (artificial life support devices or systems; surgical implantations; etc.), or may cause serious property damage (space system; undersea repeaters; nuclear power control systems; aircraft control systems; key plant systems; military equipment; etc.). Renesas Electronics disclaims any and all liability for any damages or losses incurred by you or any third parties arising from the use of any Renesas Electronics product that is inconsistent with any Renesas Electronics data sheet, user's manual or other Renesas Electronics document.
7. No semiconductor product is absolutely secure. Notwithstanding any security measures or features that may be implemented in Renesas Electronics hardware or software products, Renesas Electronics shall have absolutely no liability arising out of any vulnerability or security breach, including but not limited to any unauthorized access to or use of a Renesas Electronics product or a system that uses a Renesas Electronics product. RENESAS ELECTRONICS DOES NOT WARRANT OR GUARANTEE THAT RENESAS ELECTRONICS PRODUCTS, OR ANY SYSTEMS CREATED USING RENESAS ELECTRONICS PRODUCTS WILL BE INVULNERABLE OR FREE FROM CORRUPTION, ATTACK, VIRUSES, INTERFERENCE, HACKING, DATA LOSS OR THEFT, OR OTHER SECURITY INTRUSION ("Vulnerability Issues"). RENESAS ELECTRONICS DISCLAIMS ANY AND ALL RESPONSIBILITY OR LIABILITY ARISING FROM OR RELATED TO ANY VULNERABILITY ISSUES. FURTHERMORE, TO THE EXTENT PERMITTED BY APPLICABLE LAW, RENESAS ELECTRONICS DISCLAIMS ANY AND ALL WARRANTIES, EXPRESS OR IMPLIED, WITH RESPECT TO THIS DOCUMENT AND ANY RELATED OR ACCOMPANYING SOFTWARE OR HARDWARE, INCLUDING BUT NOT LIMITED TO THE IMPLIED WARRANTIES OF MERCHANTABILITY, OR FITNESS FOR A PARTICULAR PURPOSE.
8. When using Renesas Electronics products, refer to the latest product information (data sheets, user's manuals, application notes, "General Notes for Handling and Using Semiconductor Devices" in the reliability handbook, etc.), and ensure that usage conditions are within the ranges specified by Renesas Electronics with respect to maximum ratings, operating power supply voltage range, heat dissipation characteristics, installation, etc. Renesas Electronics disclaims any and all liability for any malfunctions, failure or accident arising out of the use of Renesas Electronics products outside of such specified ranges.
9. Although Renesas Electronics endeavors to improve the quality and reliability of Renesas Electronics products, semiconductor products have specific characteristics, such as the occurrence of failure at a certain rate and malfunctions under certain use conditions. Unless designated as a high reliability product or a product for harsh environments in a Renesas Electronics data sheet or other Renesas Electronics document, Renesas Electronics products are not subject to radiation resistance design. You are responsible for implementing safety measures to guard against the possibility of bodily injury, injury or damage caused by fire, and/or danger to the public in the event of a failure or malfunction of Renesas Electronics products, such as safety design for hardware and software, including but not limited to redundancy, fire control and malfunction prevention, appropriate treatment for aging degradation or any other appropriate measures. Because the evaluation of microcomputer software alone is very difficult and impractical, you are responsible for evaluating the safety of the final products or systems manufactured by you.
10. Please contact a Renesas Electronics sales office for details as to environmental matters such as the environmental compatibility of each Renesas Electronics product. You are responsible for carefully and sufficiently investigating applicable laws and regulations that regulate the inclusion or use of controlled substances, including without limitation, the EU RoHS Directive, and using Renesas Electronics products in compliance with all these applicable laws and regulations. Renesas Electronics disclaims any and all liability for damages or losses occurring as a result of your noncompliance with applicable laws and regulations.
11. Renesas Electronics products and technologies shall not be used for or incorporated into any products or systems whose manufacture, use, or sale is prohibited under any applicable domestic or foreign laws or regulations. You shall comply with any applicable export control laws and regulations promulgated and administered by the governments of any countries asserting jurisdiction over the parties or transactions.
12. It is the responsibility of the buyer or distributor of Renesas Electronics products, or any other party who distributes, disposes of, or otherwise sells or transfers the product to a third party, to notify such third party in advance of the contents and conditions set forth in this document.
13. This document shall not be reprinted, reproduced or duplicated in any form, in whole or in part, without prior written consent of Renesas Electronics.
14. Please contact a Renesas Electronics sales office if you have any questions regarding the information contained in this document or Renesas Electronics products.

(Note1) "Renesas Electronics" as used in this document means Renesas Electronics Corporation and also includes its directly or indirectly controlled subsidiaries.

(Note2) "Renesas Electronics product(s)" means any product developed or manufactured by or for Renesas Electronics.

(Rev.5.0-1 October 2020)

## Corporate Headquarters

TOYOSU FORESIA, 3-2-24 Toyosu,  
Koto-ku, Tokyo 135-0061, Japan

[www.renesas.com](http://www.renesas.com)

## Trademarks

Renesas and the Renesas logo are trademarks of Renesas Electronics Corporation. All trademarks and registered trademarks are the property of their respective owners.

## Contact information

For further information on a product, technology, the most up-to-date version of a document, or your nearest sales office, please visit:

[www.renesas.com/contact/](http://www.renesas.com/contact/).